

# 74HC3G06; 74HCT3G06

## Triple inverter with open-drain outputs

Rev. 4 — 19 December 2013

Product data sheet

### 1. General description

The 74HC3G06; 74HCT3G06 is a triple inverter with open-drain outputs. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

### 2. Features and benefits

- Wide supply voltage range from 2.0 V to 6.0 V
- Input levels:
  - ◆ For 74HC3G06: CMOS level
  - ◆ For 74HCT3G06: TTL level
- Complies with JEDEC standard no. 7A
- High noise immunity
- Low power dissipation
- Multiple package options
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

### 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC3G06DP 74HCT3G06DP	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP8	plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm	SOT505-2
74HC3G06DC 74HCT3G06DC	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	VSSOP8	plastic very thin shrink small outline package; 8 leads; body width 2.3 mm	SOT765-1
74HC3G06GD 74HCT3G06GD	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body $3 \times 2 \times 0.5\text{ mm}$	SOT996-2



4. Marking

Table 2. Marking code

Type number	Marking code <sup>[1]</sup>
74HC3G06DP	H06
74HCT3G06DP	T06
74HC3G06DC	H06
74HCT3G06DC	T06
74HC3G06GD	H06
74HCT3G06GD	T06

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

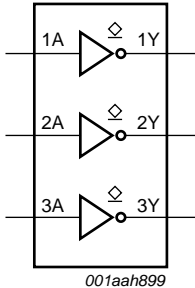


Fig 1. Logic symbol

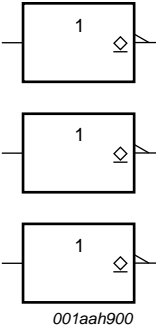


Fig 2. IEC logic symbol

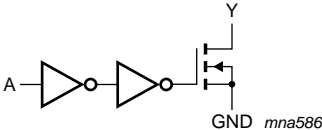


Fig 3. Logic diagram (one inverter)

6. Pinning information

6.1 Pinning

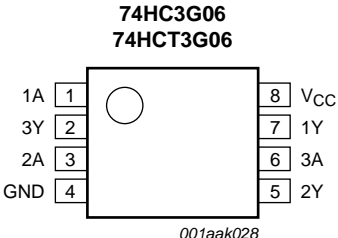


Fig 4. Pin configuration SOT505-2 (TSSOP8) and SOT765-1 (VSSOP8)

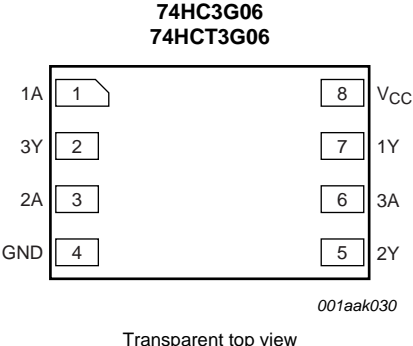


Fig 5. Pin configuration SOT996-2 (XSON8)

## 6.2 Pin description

**Table 3.** Pin description

Symbol	Pin	Description
1A, 2A, 3A	1, 3, 6	data input
GND	4	ground (0 V)
1Y, 2Y, 3Y	7, 5, 2	data output
V <sub>CC</sub>	8	supply voltage

## 7. Functional description

**Table 4.** Function table<sup>[1]</sup>

Input nA	Output nY
L	Z
H	L

[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state.

## 8. Limiting values

**Table 5.** Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	7.0	V
I <sub>IK</sub>	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	<sup>[1]</sup> -	±20	mA
I <sub>OK</sub>	output clamping current	$V_O < -0.5\text{ V}$	<sup>[1]</sup> -20	-	mA
V <sub>O</sub>	output voltage	active mode	<sup>[1]</sup> -0.5	V <sub>CC</sub> + 0.5	V
		high-impedance mode	<sup>[1]</sup> -0.5	7.0	V
I <sub>O</sub>	output current	$V_O = -0.5\text{ V}$ to $7.0\text{ V}$	<sup>[1]</sup> -	25	mA
I <sub>CC</sub>	supply current		<sup>[1]</sup> -	50	mA
I <sub>GND</sub>	ground current		<sup>[1]</sup> -50	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>D</sub>	dynamic power dissipation	T <sub>amb</sub> = -40 °C to +125 °C	<sup>[2]</sup> -	300	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP8 package: above 55 °C the value of P<sub>tot</sub> derates linearly with 2.5 mW/K.  
 For VSSOP8 package: above 110 °C the value of P<sub>tot</sub> derates linearly with 8 mW/K.  
 For XSON8 package: above 118 °C the value of P<sub>tot</sub> derates linearly with 7.8 mW/K.

## 9. Recommended operating conditions

**Table 6. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74HC3G06			74HCT3G06			Unit
			Min	Typ	Max	Min	Typ	Max	
$V_{CC}$	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
$V_I$	input voltage		0	-	6.0	0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0\text{ V}$	-	-	625	-	-	-	ns/V
		$V_{CC} = 4.5\text{ V}$	-	1.67	139	-	1.67	139	ns/V
		$V_{CC} = 6.0\text{ V}$	-	-	83	-	-	-	ns/V

## 10. Static characteristics

**Table 7. Static characteristics**

Voltages are referenced to GND (ground = 0 V). All typical values are measured at  $T_{amb} = 25\text{ °C}$ .

Symbol	Parameter	Conditions	−40 °C to +85 °C			−40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
74HC3G06								
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>						
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.33	-	0.4	V
		I <sub>O</sub> = 5.2 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	μA
I <sub>LO</sub>	output leakage current	V <sub>I</sub> = V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND	-	-	±5.0	-	±10	μA
I <sub>CC</sub>	supply current	per input pin; V <sub>CC</sub> = 6.0 V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A;	-	-	10	-	20	μA
C <sub>I</sub>	input capacitance		-	1.5	-	-	-	pF

**Table 7. Static characteristics ...continued**

Voltages are referenced to GND (ground = 0 V). All typical values are measured at  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	−40 °C to +85 °C			−40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
74HCT3G06								
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>						
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±1.0	-	±1.0	μA
I <sub>LO</sub>	output leakage current	V <sub>I</sub> = V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND	-	-	±5.0	-	±10	μA
I <sub>CC</sub>	supply current	per input pin; V <sub>CC</sub> = 5.5 V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A;	-	-	10	-	20	μA
ΔI <sub>CC</sub>	additional supply current	per input; V <sub>CC</sub> = 4.5 V to 5.5 V; V <sub>I</sub> = V <sub>CC</sub> − 2.1 V; I <sub>O</sub> = 0 A	-	-	375	-	410	μA
C <sub>I</sub>	input capacitance		-	1.5	-	-	-	pF

[1] Typical values are measured at  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); all typical values are measured at  $T_{amb} = 25\text{ }^{\circ}\text{C}$ ; for test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	−40 °C to +85 °C			−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	
74HC3G06								
t <sub>PZL</sub>	OFF-state to LOW propagation delay	nA to nY; see <a href="#">Figure 6</a>						
		V <sub>CC</sub> = 2.0 V	-	22	95	-	125	ns
		V <sub>CC</sub> = 4.5 V	-	9	18	-	25	ns
		V <sub>CC</sub> = 6.0 V	-	8	16	-	20	ns
t <sub>PLZ</sub>	LOW to OFF-state propagation delay	nA to nY; see <a href="#">Figure 6</a>						
		V <sub>CC</sub> = 2.0 V	-	24	95	-	125	ns
		V <sub>CC</sub> = 4.5 V	-	11	20	-	27	ns
		V <sub>CC</sub> = 6.0 V	-	10	19	-	23	ns
t <sub>THL</sub>	HIGH to LOW output transition time	nY; see <a href="#">Figure 6</a>						
		V <sub>CC</sub> = 2.0 V	-	18	95	-	125	ns
		V <sub>CC</sub> = 4.5 V	-	6	19	-	25	ns
		V <sub>CC</sub> = 6.0 V	-	5	16	-	20	ns
C <sub>PD</sub>	power dissipation capacitance	V <sub>I</sub> = GND to V <sub>CC</sub> <a href="#">[1]</a>	-	4	-	-	-	pF

**Table 8. Dynamic characteristics ...continued**

Voltages are referenced to GND (ground = 0 V); all typical values are measured at  $T_{amb} = 25\text{ }^{\circ}\text{C}$ ; for test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	
74HCT3G06								
t <sub>PZL</sub>	OFF-state to LOW propagation delay	nA to nY; see <a href="#">Figure 6</a> V <sub>CC</sub> = 4.5 V	-	9	24	-	29	ns
t <sub>PLZ</sub>	LOW to OFF-state propagation delay	nA to nY; see <a href="#">Figure 6</a> V <sub>CC</sub> = 4.5 V	-	12	27	-	32	ns
t <sub>THL</sub>	HIGH to LOW output transition time	V <sub>CC</sub> = 4.5 V; see <a href="#">Figure 6</a>	-	6	19	-	22	ns
C <sub>PD</sub>	power dissipation capacitance	V <sub>I</sub> = GND to V <sub>CC</sub> – 1.5 V <a href="#">[1]</a>	-	4		-	-	pF

[1]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

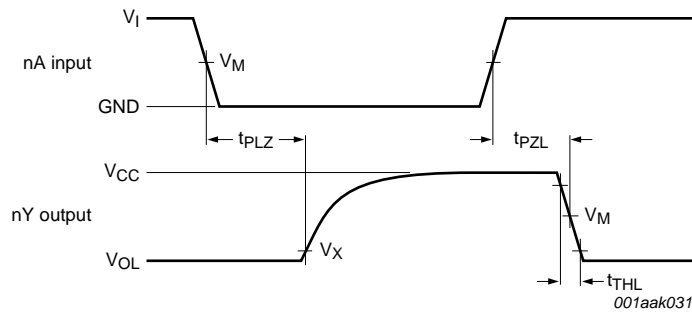
$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in V;

$N$  = number of inputs switching;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

## 12. Waveforms



Measurement points are given in [Table 9](#).

$V_{OL}$  is the typical output voltage level that occurs with the output load.

**Fig 6. The input (nA) to output (nY) propagation delays**

**Table 9. Measurement points**

Type	Input	Output	
	$V_M$	$V_M$	$V_X$
74HC3G06	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$0.1 \times V_{CC}$
74HCT3G06	1.3 V	1.3 V	$0.1 \times V_{CC}$

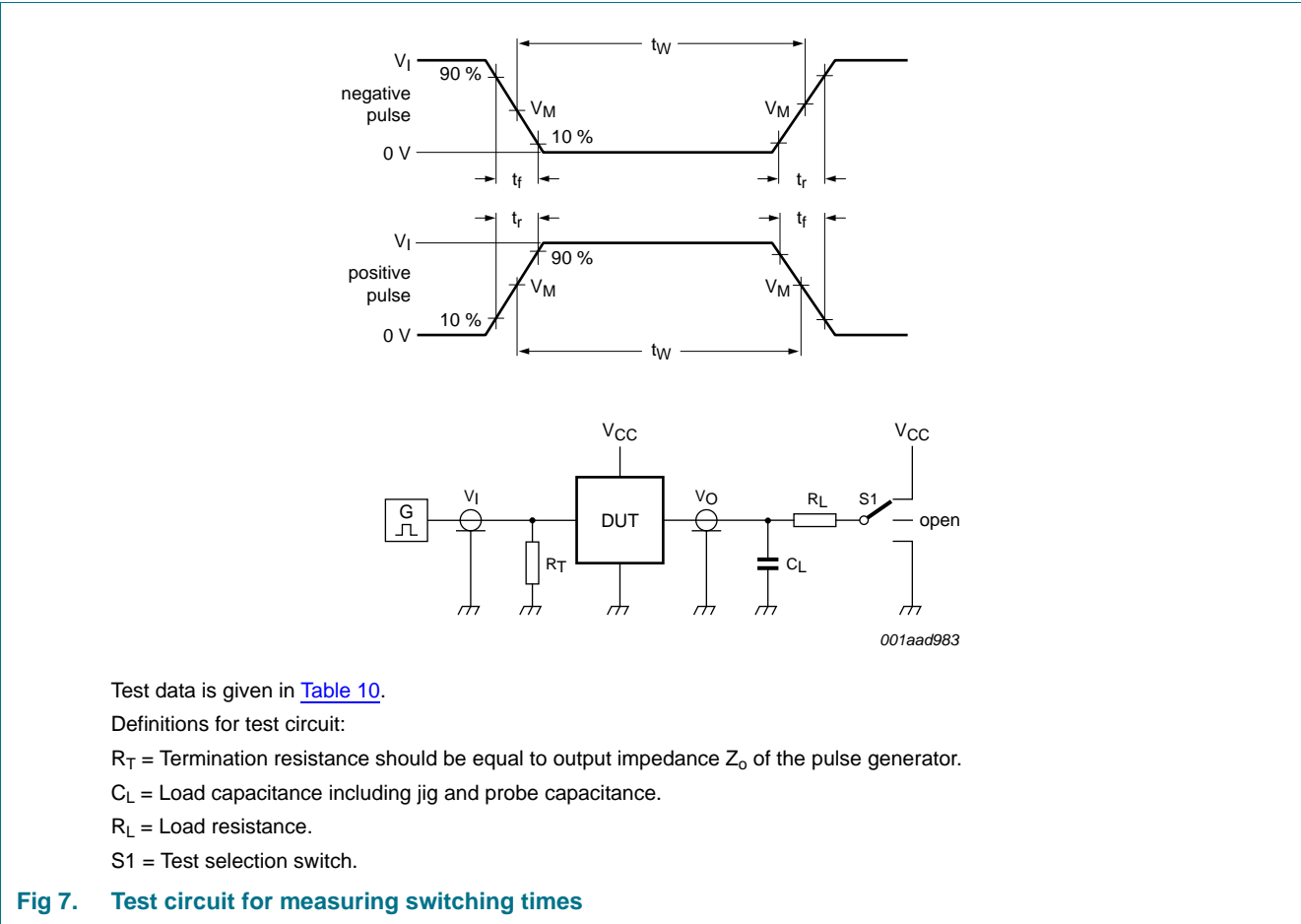


Table 10. Test data

Type	Input		Load		S1 position
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	
74HC3G06	GND to $V_{CC}$	$\leq 6$ ns	50 pF	1 k $\Omega$	$V_{CC}$
74HCT3G06	GND to 3 V	$\leq 6$ ns	50 pF	1 k $\Omega$	$V_{CC}$

13. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2

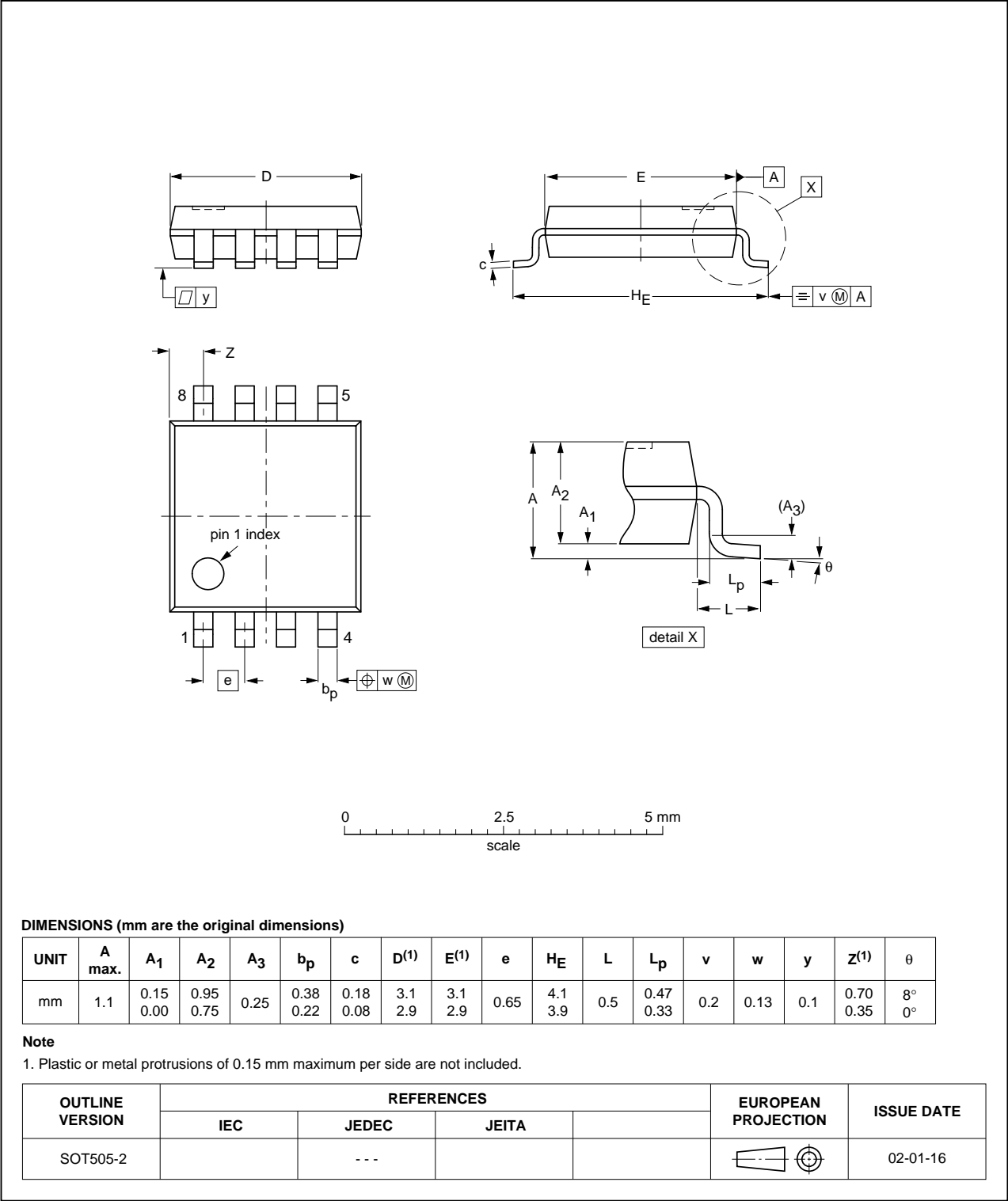


Fig 8. Package outline SOT505-2 (TSSOP8)



VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1

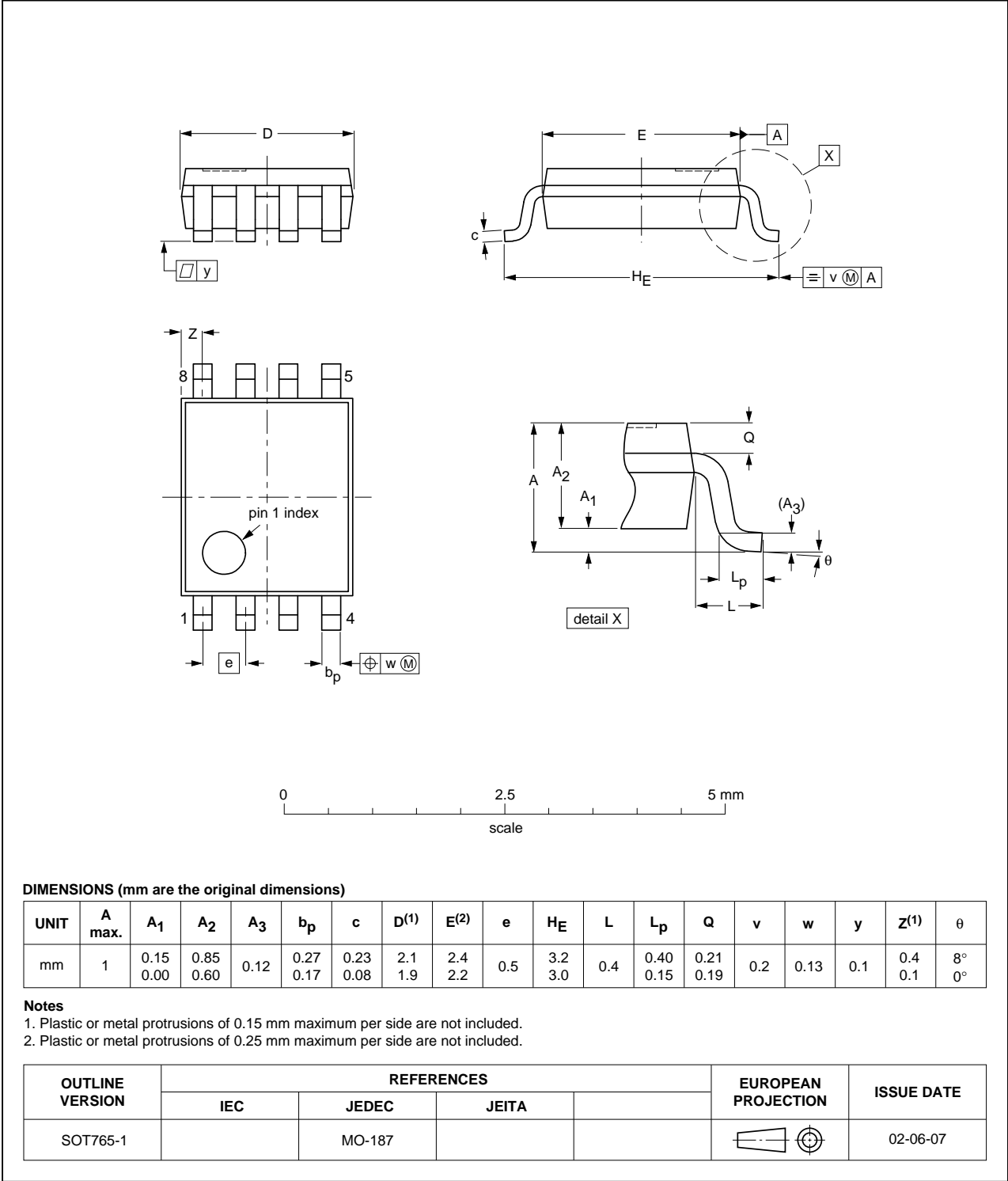


Fig 9. Package outline SOT765-1 (VSSOP8)

XSON8: plastic extremely thin small outline package; no leads;  
8 terminals; body 3 x 2 x 0.5 mm

SOT996-2

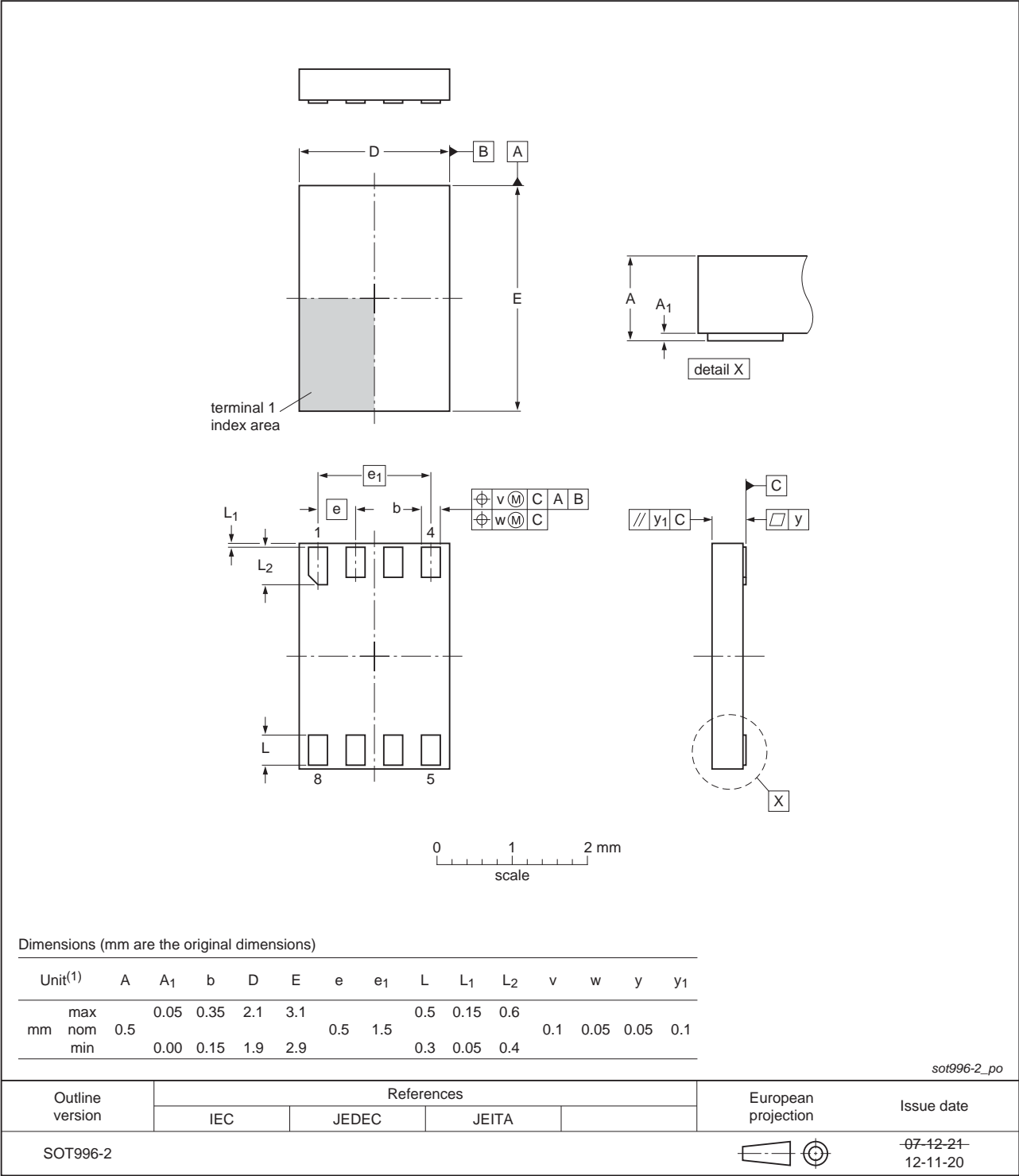


Fig 10. Package outline SOT996-2 (XSON8)

## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT3G06 v.4	20131219	Product data sheet	-	74HC_HCT3G06 v.3
Modifications:	• For type numbers 74HC3G06GD and 74HCT3G06GD XSON8U has changed to XSON8.			
74HC_HCT3G06 v.3	20090511	Product data sheet	-	74HC_HCT3G06 v.2
74HC_HCT3G06 v.2	20031202	Product specification	-	74HC_HCT3G06 v.1
74HC_HCT3G06 v.1	20030515	Product specification	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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